

Data Sheet	January 2000	File Number	3740.2

#### 50A, 1200V Ultrafast Diode

The RURG50120 is an ultrafast diode with soft recovery characteristics ( $t_{rr}$  < 125ns). It has low forward voltage drop and is of silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of switching power supplies and other power switching applications. Its low stored charge and ultrafast soft recovery minimizes ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

Formerly developmental type TA49099.

## **Ordering Information**

PART NUMBER	PACKAGE	BRAND	
RURG50120	TO-247	RURG50120	

NOTE: When ordering, use the entire part number.

## Symbol



#### **Features**

•	Ultrafast with Soft Recovery <125ns
•	Operating Temperature
•	Reverse Voltage

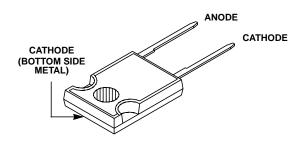
- · Avalanche Energy Rated
- Planar Construction

## **Applications**

- · Switching Power Supplies
- · Power Switching Circuits
- · General Purpose

### **Packaging**

**JEDEC STYLE 2 LEAD TO-247** 



### **Absolute Maximum Ratings** T<sub>C</sub> = 25°C, Unless Otherwise Specified

	RURG50120	UNITS
Peak Repetitive Reverse VoltageV <sub>RRM</sub>	1200	V
Working Peak Reverse Voltage	1200	V
DC Blocking Voltage	1200	V
Average Rectified Forward Current $I_{F(AV)}$ ( $T_C = 85^{\circ}C$ )	50	Α
Repetitive Peak Surge Current	100	Α
Nonrepetitive Peak Surge Current	500	Α
Maximum Power Dissipation	170	W
Avalanche Energy (See Figures 10 and 11)	50	mJ
Operating and Storage Temperature	-65 to 175	οС

**Electrical Specifications**  $T_C = 25^{\circ}C$ , Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 50A	-	-	2.1	V
	$I_F = 50A, T_C = 150^{\circ}C$	-	-	1.9	V
I <sub>R</sub>	V <sub>R</sub> = 1200V	-	-	250	μΑ
	$V_R = 1200V, T_C = 150^{\circ}C$	-	-	2.0	mA
t <sub>rr</sub>	$I_F = 1A$ , $dI_F/dt = 100A/\mu s$	-	-	125	ns
	$I_F = 50A$ , $dI_F/dt = 100A/\mu s$	-	-	200	ns
t <sub>a</sub>	$I_F = 50A$ , $dI_F/dt = 100A/\mu s$	-	95	-	ns
t <sub>b</sub>	I <sub>F</sub> = 50A, dI <sub>F</sub> /dt = 100A/μs	-	70	-	ns
Q <sub>RR</sub>	$I_F = 50A$ , $dI_F/dt = 100A/\mu s$	-	800	-	nC
СЈ	V <sub>R</sub> = 10V, I <sub>F</sub> = 0A	-	160	-	pF
$R_{ heta JC}$		-	-	0.9	°C/W

#### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

 $I_R$  = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (See Figure 9), summation of  $t_a + t_b$ .

t<sub>a</sub> = Time to reach peak reverse current (See Figure 9).

 $t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

Q<sub>RR</sub> = Reverse recovery charge.

 $C_J$  = Junction capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = Pulse width.

D = Duty cycle.

# **Typical Performance Curves**

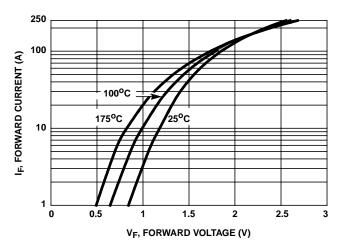


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

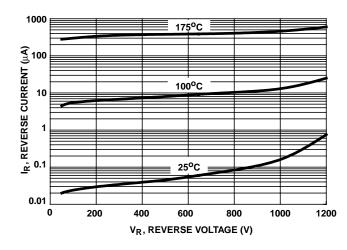


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

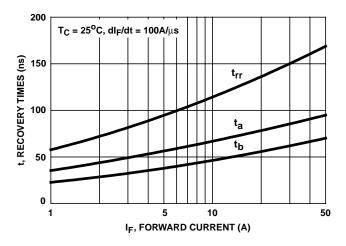


FIGURE 3.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

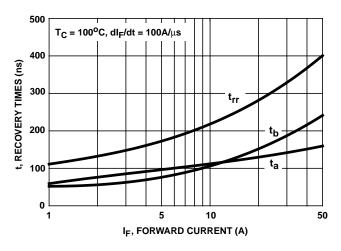


FIGURE 4.  $t_{rr}$ ,  $t_a$  and  $t_b$  curves vs forward current

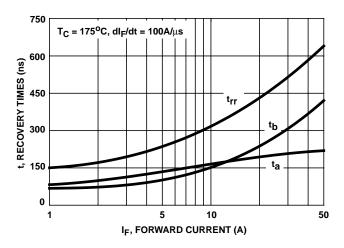


FIGURE 5.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

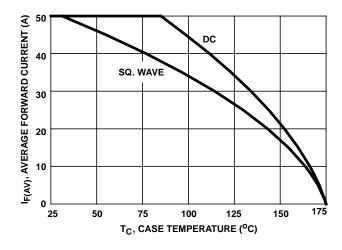


FIGURE 6. CURRENT DERATING CURVE

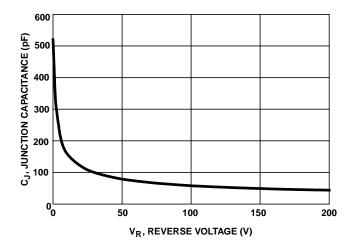


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

#### Test Circuits and Waveforms

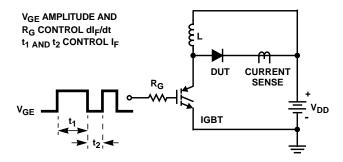


FIGURE 8. t<sub>rr</sub> TEST CIRCUIT

I = 1.6A L = 40mH  $R < 0.1\Omega$   $E_{AVL} = 1/2LI^2 \left[ V_{R(AVL)} / (V_{R(AVL)} - V_{DD}) \right]$   $Q_1 = IGBT \left( BV_{CES} > DUT \ V_{R(AVL)} \right)$  CURRENT + 0  $SENSE V_{DD}$   $V_{DD}$   $V_{DD}$ 

FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

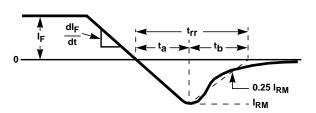


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

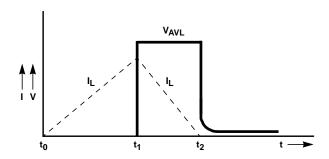


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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